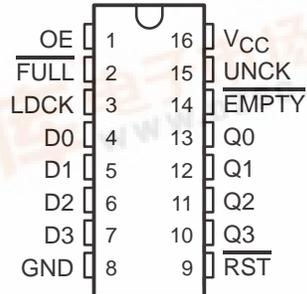


SN74ALS232B 16 × 4 ASYNCHRONOUS FIRST-IN, FIRST-OUT MEMORY

SCAS251B – FEBRUARY 1989 – REVISED APRIL 1998

- **Independent Asynchronous Inputs and Outputs**
- **16 Words by 4 Bits**
- **Data Rates up to 40 MHz**
- **Fall-Through Time 14 ns Typical**
- **3-State Outputs**
- **Package Options Include Plastic Small-Outline Package (DW), Plastic Chip Carriers (FN), and Standard Plastic 300-mil DIPs (N)**

DW OR N PACKAGE
(TOP VIEW)



description

This 64-bit memory features high speed and fast fall-through times. It is organized as 16 words by 4 bits.

A first-in, first-out (FIFO) memory is a storage device that allows data to be written into and read from its array at independent data rates. This FIFO is designed to process data at rates up to 40 MHz in a bit-parallel format, word by word.

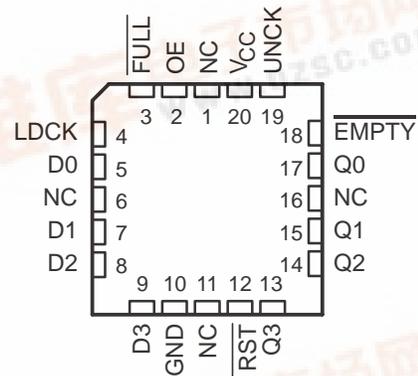
Data is written into memory on a low-to-high transition at the load-clock (LDCK) input and is read out on a low-to-high transition at the unload-clock (UNCK) input. The memory is full when the number of words clocked in exceeds by 16 the number of words clocked out. When the memory is full, LDCK signals have no effect on the data residing in memory. When the memory is empty, UNCK signals have no effect.

Status of the FIFO memory is monitored by the FULL and EMPTY output flags. The FULL output is low when the memory is full and high when it is not full. The EMPTY output is low when the memory is empty and high when it is not empty.

A low level on the reset (RST) input resets the internal stack-control pointers and also sets EMPTY low and sets FULL high. The Q outputs are not reset to any specific logic level. The first low-to-high transition on LDCK, after either a RST pulse or from an empty condition, causes EMPTY to go high and the data to appear on the Q outputs. It is important to note that the first word does not have to be unloaded. Data outputs are noninverting with respect to the data inputs and are at high impedance when the output-enable (OE) input is low. OE does not affect the FULL or EMPTY output flags. Cascading is easily accomplished in the word-width direction but is not possible in the word-depth direction.

The SN74ALS232B is characterized for operation from 0°C to 70°C.

FN PACKAGE
(TOP VIEW)



NC – No internal connection

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



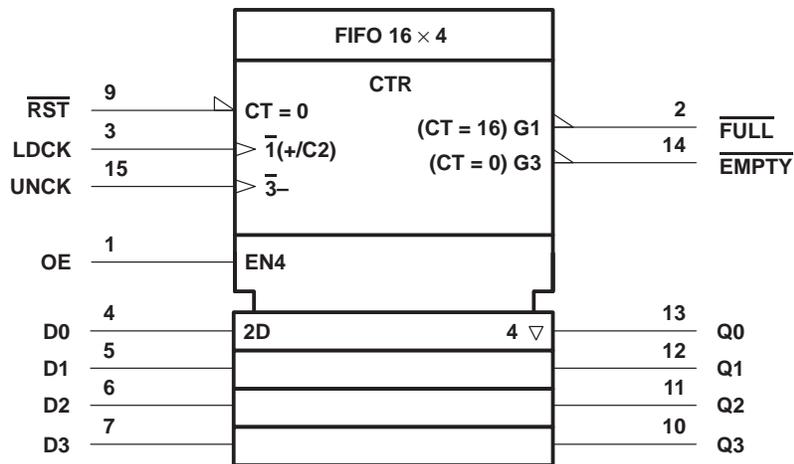
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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logic symbol†



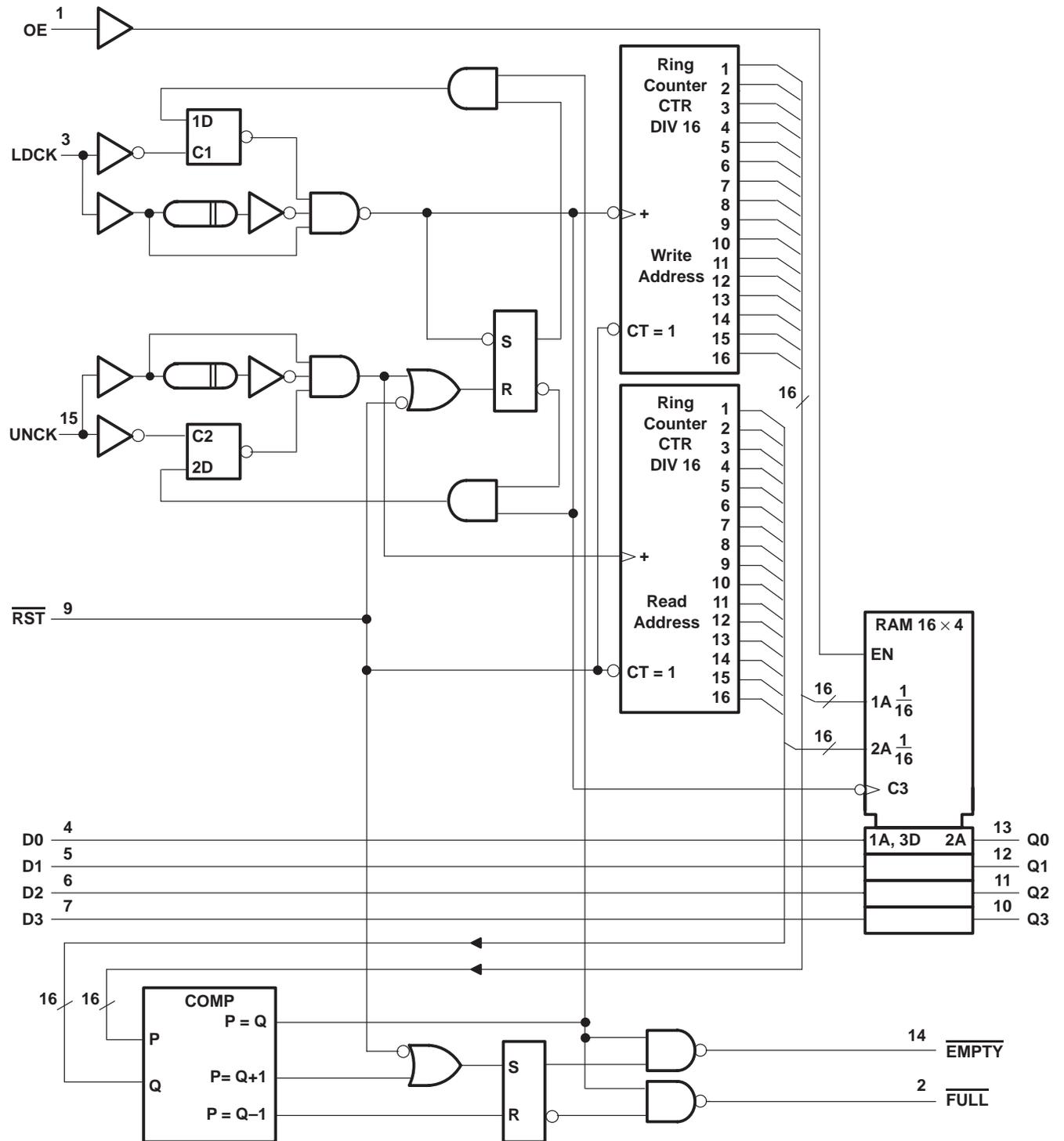
† This symbol is in accordance with ANSI/IEEE Standard 91-1984 and IEC Publication 617-12. The symbol is functionally accurate but does not show the details of implementation; for these, see the logic diagram. The symbol represents the memory as if it were controlled by a single counter whose content is the number of words stored at the time. Output data is invalid when the counter content (CT) is 0. Pin numbers shown are for the DW and N packages.

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logic diagram (positive logic)



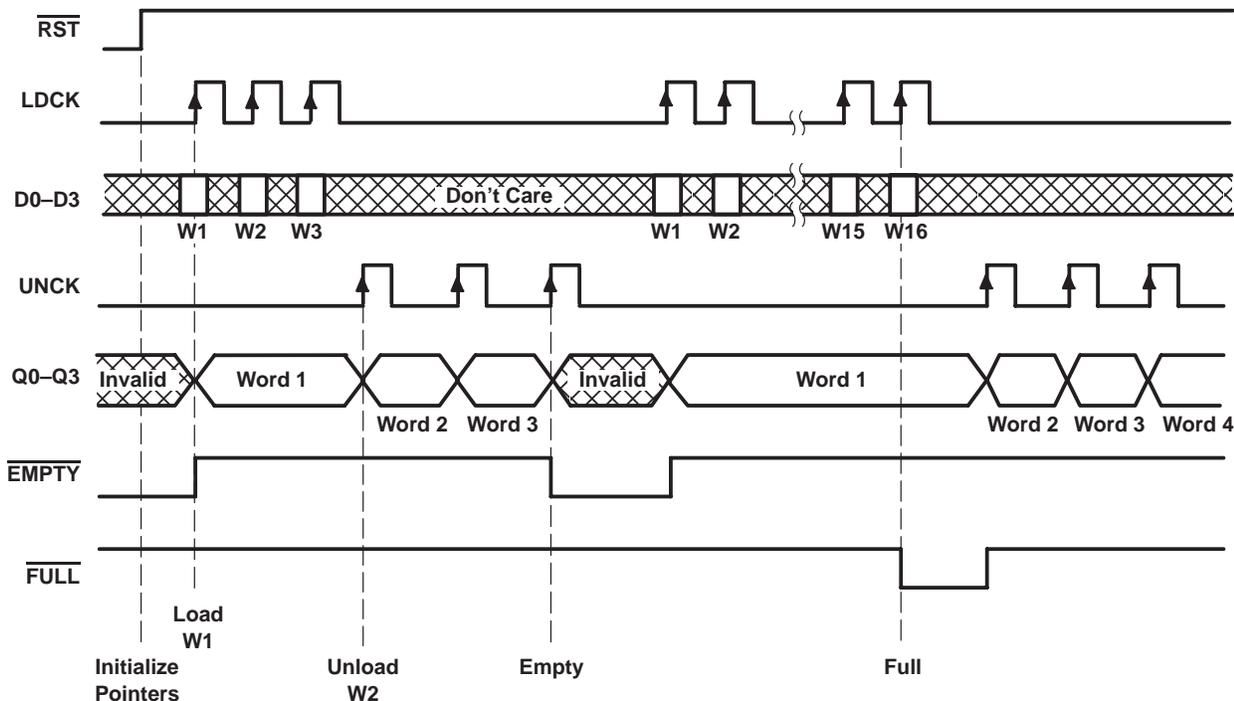
Pin numbers shown are for the DW and N packages.

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timing diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I	-0.5 V to 7 V
Voltage range applied to a disabled 3-state output	-0.5 V to 5.5 V
Package thermal impedance, θ_{JA} (see Note 2): DW package	105°C/W
FN package	83°C/W
N package	78°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to GND.
 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current	Q outputs		-2.6	mA
		FULL, EMPTY		-0.4	
I _{OL}	Low-level output current	Q outputs		24	mA
		FULL, EMPTY		8	
T _A	Operating free-air temperature	0		70	°C

NOTE 3: To ensure proper operation of this high-speed FIFO device, it is necessary to provide a clean signal to the LDCK and UNCK clock inputs. Any excessive noise or glitching on the clock inputs that violates limits for maximum V_{IL}, minimum V_{IH}, or minimum pulse duration can cause a false clock or improper operation of the internal read and write pointers.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2	V
V _{OH}	Q outputs	V _{CC} = 4.5 V,	I _{OH} = -2.6 mA	2.4	3.2		V
	FULL, EMPTY	V _{CC} = 4.5 V to 5.5 V,	I _{OH} = -0.4 mA	V _{CC} -2			
V _{OL}	Q outputs	V _{CC} = 4.5 V	I _{OL} = 12 mA	0.25	0.4	V	
			I _{OL} = 24 mA	0.35	0.5		
	FULL, EMPTY	V _{CC} = 4.5 V	I _{OL} = 4 mA	0.25	0.4		
			I _{OL} = 8 mA	0.35	0.5		
I _{OZH}		V _{CC} = 5.5 V,	V _O = 2.7 V			20	μA
I _{OZL}		V _{CC} = 5.5 V,	V _O = 0.4 V			-20	μA
I _I		V _{CC} = 5.5 V,	V _I = 7 V			0.1	mA
I _{IH}		V _{CC} = 5.5 V,	V _I = 2.7 V			20	μA
I _{IL}		V _{CC} = 5.5 V,	V _I = 0.4 V			-0.2	mA
I _{O‡}		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
I _{CC}		V _{CC} = 5.5 V			80	125	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS}.

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timing requirements over recommended operating free-air temperature range (see Figure 1)

		MIN	NOM	MAX	UNIT
f _{clock} [†]	Clock frequency			40	MHz
				40	
t _w	Pulse duration	RST [−] low		18	ns
		LDCK low		15	
		LDCK high		10	
		UNCK low		15	
		UNCK high		10	
t _{su}	Setup time	Data before LDCK [↑]		8	ns
		LDCK inactive before RST [↑]		5	
t _h	Hold time	Data after LDCK [↑]		5	ns
		LDCK inactive after RST [↑]		5	

[†] The maximum possible clock frequency is 40 MHz. The maximum clock frequency when using a 50% duty cycle is 33.3 MHz.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP [‡]	MAX	MIN	MAX	UNIT
f _{max}	LDCK, UNCK			50		40		MHz
t _{pd}	LDCK [↑]	Any Q		14	23	6	30	ns
	UNCK [↑]			15	23	6	30	
t _{PLH}	LDCK [↑]	EMPTY		13	20	5	25	ns
t _{PHL}	UNCK [↑]	EMPTY		15	22	6	27	ns
	RST [−] ↓			15	21	5	26	
	LDCK [↑]		FULL		15	22	6	
t _{PLH}	UNCK [↑]	FULL		13	20	5	25	ns
	RST [−] ↓			16	23	7	28	
t _{en}	OE [↑]	Q		5	12	1	14	ns
t _{dis}	OE [↓]	Q		5	12	1	16	ns

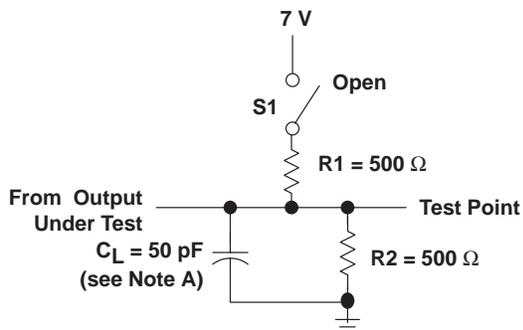
[‡] Typical values at V_{CC} = 5 V, T_A = 25°C.

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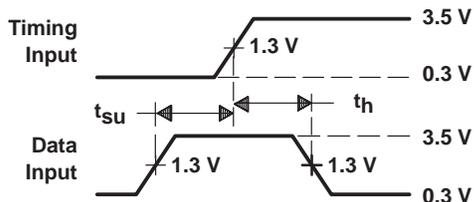
PARAMETER MEASUREMENT INFORMATION



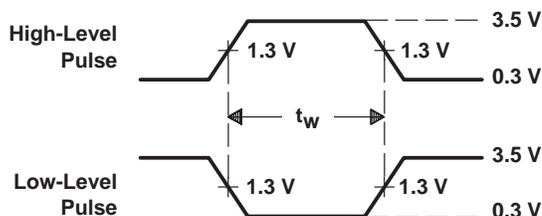
LOAD CIRCUIT FOR 3-STATE OUTPUTS

SWITCH POSITION TABLE

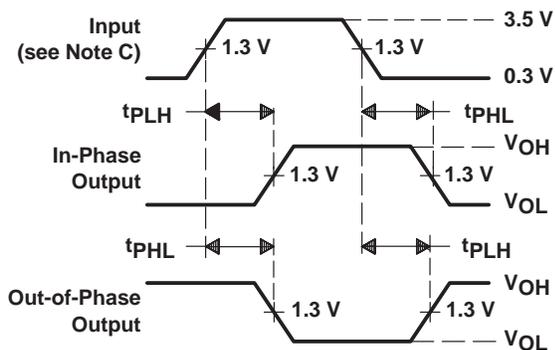
PARAMETER	S1
t_{en}	t_{PZH} Open
	t_{PZL} Closed
t_{dis}	t_{PHZ} Open
	t_{PLZ} Closed
t_{pd}	t_{PLH} Open
	t_{PHL} Open



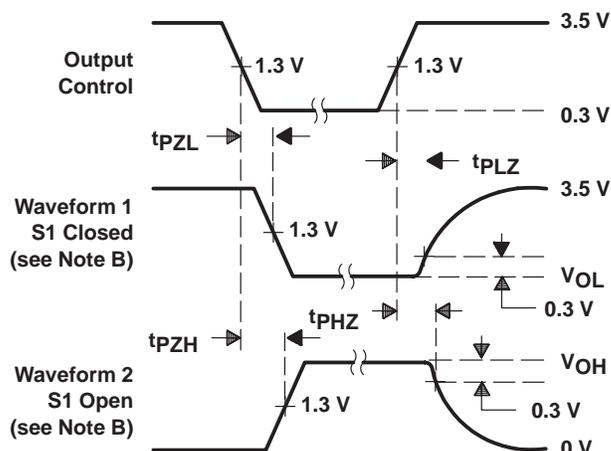
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50 \Omega$, $t_r \leq 2$ ns, $t_f \leq 2$ ns.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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